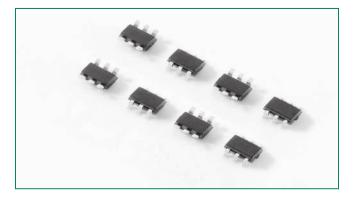


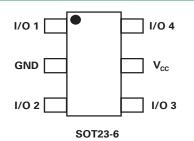
SP0504S Series 0.85pF Diode Array



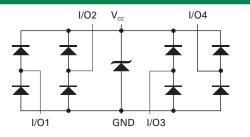
Description

The SP0504S integrates low capacitance rail-to-rail diodes with an integrated proprietary avalanche breakdown diode that protects applications against ESD, EFT and low surge events. This component is rated for the maximum IEC 61000-4-2 ESD (level 4) contact and air discharge events. Their very low off-state capacitance also makes them ideal for protecting high speed signal pins such as HDMI, DVI, USB2.0, and IEEE 1394.

Pinout



Functional Block Diagram



Additional Information







Features

- RoHS compliant and lead-free
- Low off-state capacitance of 0.85 pF (TYP) per I/O
- ESD rating of ±12kV contact discharge, ±15kV air discharge, (IEC 61000-4-2)
- EFT protection, IEC 61000-4-4, 40A

- (5/50ns)
- Low leakage current of 0.5µA (MAX) at 5V

(P6) GREEN

RoHS

- Small packaging options saves board space
- Lightning, 4.5A (8/20µs as defined in IEC 61000-4-5 2nd edition)

• Network Hardware/Ports

• AEC-Q101 qualified

Test Equipment

Medical EquipmentAutomotive Network

Applications

- Computer Peripherals
- Mobile Phones
- PDA's
- Digital Cameras

Application Example

RJ-45 Connector Ethernet PHY

A single 4 channel SP0504S component can be used to protect four of the data lines in a HDMI/DVI interface. Two (2) SP0504S components provide protection for the main data lines. Low voltage ASIC HDMI/DVI drivers can also be protected with the SP0504S, the +V_{cc} pins on the SP0504S can be substituted with a suitable bypass capacitor or in some backdrive applications the +V_{cc} of the SP0504S can be floated or NC.

Life Support Note:

Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.



Absolute Maximum Ratings

Symbol	Parameter	Value	Units			
I _{PP}	Peak Current (t _p =8/20µs)	4.5	А			
T _{op}	Operating Temperature	-40 to 125	°C			
T _{STOR}	Storage Temperature	–55 to 150	°C			

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

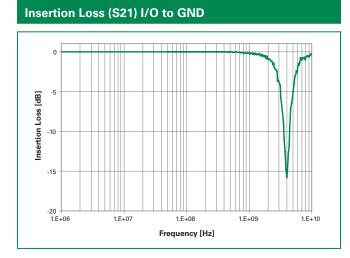
Electrical Characteristics (T_{OP}=25°C)

	рр - ^с					
Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Reverse Standoff Voltage	V _{RWM}	$I_{R} = 1 \mu A$	-	-	6.0	V
Reverse Leakage Current	I	V _R =5V	-	-	0.5	μA
Breakdown Voltage	V _{BR}	I _R =1mA	6.3	8	8.8	V
Clamp Voltage ¹	V _c	I_{pp} =1A, t _p =8/20µs, I/O to GND	-	9.5	11.0	V
		I_{pp} =2A, t_p =8/20µs, I/O to GND	-	10.6	13.0	V
ESD Withstand Voltage ¹	V _{ESD}	IEC 61000-4-2 (Contact)	±12	-	-	kV
		IEC 61000-4-2 (Air)	±15	-	-	kV
Diode Capacitance ¹		Reverse Bias=0V, f=1MHz	0.95	1.1	1.25	pF
	C _{I/O-GND}	Reverse Bias=1.65V, f=1MHz	0.7	0.85	1.0	pF
Diode Capacitance ¹	C _{I/O-I/O}	Reverse Bias=0V, f=1MHz	-	0.5	-	рF

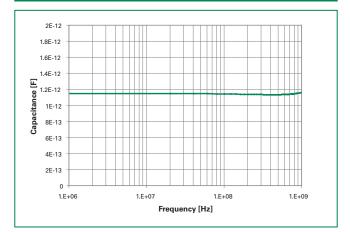
Note: 1. Parameter is guaranteed by design and/or component characterization.

2. Transmission Line Pulse (TLP) with 100ns width, 2ns rise time, and average window t1=70ns to t2= 90ns





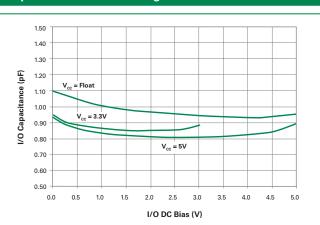
Capacitance vs. Frequency



IEC 61000 -4-2 +8 kV Contact ESD Clamping Voltage

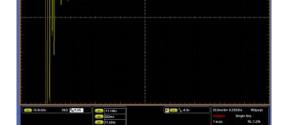


Capacitance vs. Bias Voltage



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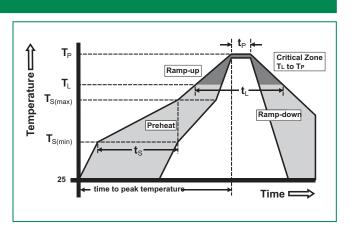
IEC 61000 -4-2 -8 kV Contact ESD Clamping Voltage



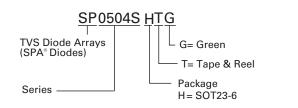


Soldering Parameters

Reflow Condition		Pb – Free assembly	
- Temperature Min (T _{s(min)})		150°C	
Pre Heat	- Temperature Max (T _{s(max)})	200°C	
	- Time (min to max) (t _s)	60 – 180 secs	
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max	
T _{S(max)} to T _L - Ramp-up Rate		3°C/second max	
Reflow	- Temperature (T _L) (Liquidus)	217°C	
Renow	- Temperature (t _L)	60 – 150 seconds	
Peak Temperature (T _P)		260 ^{+0/-5} °C	
Time within 5°C of actual peak Temperature (t _p)		20 – 40 seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T _P)		8 minutes Max.	
Do not exceed		260°C	

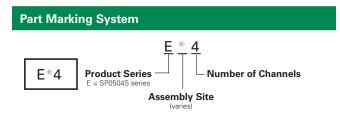


Part Numbering System



Product Characteristics

Lead Plating	Matte Tin		
Lead Material	Copper Alloy		
Lead Coplanarity	0.0004 inches (0.102mm)		
Substitute Material	Silicon		
Body Material	Molded Compund		
Flammability	UL Recognized compund meeting flammability rating V-0		

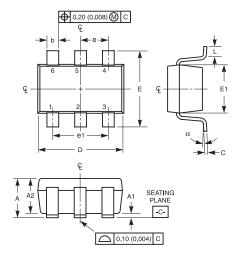


Ordering Information					
Part Number	Package	Min. Order Qty.			
SP0504SHTG	SOT23-6	3000			

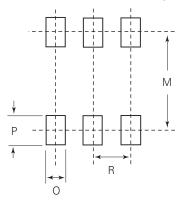


TVS Diode Arrays (SPA®Diodes) Low Capacitance ESD Protection - SP0504S Series

Package Dimensions - SOT23-6

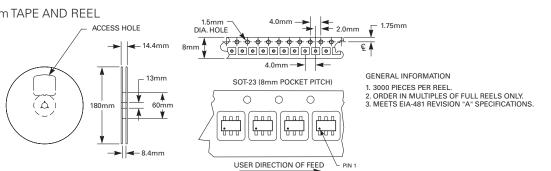


Recommended	Solder	Pad	Lavout



Embossed Carrier Tape & Reel Specification - SOT23-6

8mm TAPE AND REEL



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Package	SOT23				
Pins	6				
JEDEC	MO-178AB				
	Millimeters		Inc	Inches	
	Min	Max	Min	Max	Notes
Α	0.900	1.450	0.035	0.057	-
A1	0.000	0.150	0.000	0.006	-
A2	0.900	1.300	0.035	0.051	-
b	0.350	0.500	0.0138	0.0196	-
С	0.080	0.220	0.0031	0.009	-
D	2.800	3.000	0.11	0.118	3
E	2.600	3.000	0.102	0.118	-
E1	1.500	1.750	0.06	0.069	3
е	0.95 Ref		0.03	74 ref	-
e1	1.9 Ref		0.074	18 Ref	-
L	0.30	0.600	0.012	0.023	4,5
N	6			6	6
α	0°	8°	0°	8°	-
М		2.590		0.102	-
0		0.690		.027 TYP	-
Р		0.990		.039 TYP	-
R		0.950	ĺ	0.038	-

Notes:

1.

2.

Dimensioning and tolerancing Per ASME Y14.5M-1994. Package conforms to EIAJ SC-74 (1992). Dimensions D and E1 are exclusive of mold flash, protrusions, or gate burrs. 3.

Foot length L measured at reference to seating plane. "L" is the length of flat foot surface for soldering to substrate. "N" is the number of terminal positions. 4.

5. 6.

7 Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.